Amendments to the claims:

New text is underlined and deleted text has been struck through or double bracketed.

- 1. (currently amended) A method of manufacturing cylindrical polyalkylene embedded silane-modified-CPG devices, comprising mixing [[a]] an aqueous-free polyalkylene with a silane-modified CPG; filling cylindrical wells of an aluminum plate with said mixture; heating said plate at 180°C to 220°C for a predetermined schedule; and upon cooling, releasing from said plate said embedded devices.
- 2. (original) The method according to claim 1, in which the said polyalkylene is selected from the group consisting of ultrahigh molecular weight polyethylene, high density polyethylene, low density polyethylene, polypropylene, and mixtures thereof.
- 3. (original) The method according to claim 1, in which the quantity of the said polyalkylene is preferably from 50 to 70% by weight, based on the total weight of the resin mixture.
- 4. (original) The method according to claim 1, in which silane-modified-CPG are controlled porous glass beads which have been modified with aminoalkyltrialkoxysilane, [alkylamino]alkyl(trialkoxy)silane or mercaptoalkyl(trialkoxy)silane and mixtures thereof.
- 5. (withdrawn; currently amended) A compound of The method according to claim 4, wherein alkyl is selected from the group consisting of methyl, ethyl and propyl and wherein alkoxy is selected from the group consisting of methoxy, ethoxy and propoxy.

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- 6. (original) The method according to claim 1, wherein the said embedded devices contain less than ten micromoles of reactive amino or mercapto moieties.
- 7. (original) The method according to claim 1, wherein the said aluminum plate is drilled with 50 to 5000 cylindrical wells.

8.-20. (cancelled)

21. (previously presented) The method according to claim 1 wherein each of said released embedded devices is a cylindrically shaped plug comprising said polyalkylene and silane-modified CPG mixture, whereby said cylindrical wells of said aluminum plate act as a mold for said released embedded devices.